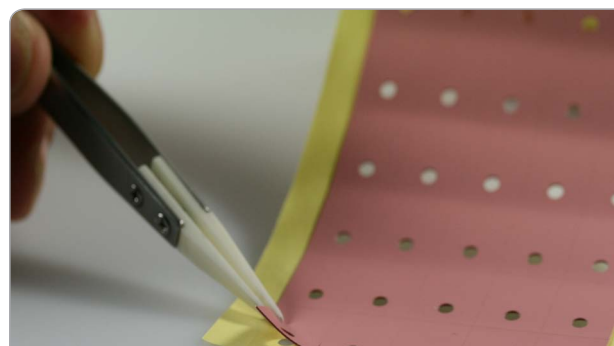


High-performance thermally conductive thermo-silicone KU-CG

HEATPAD® KU-CG is a fiberglass reinforced silicone foil filled with thermally conductive ceramics, hence its high thermal conductivity. By implementing it, a very low total thermal resistance can be achieved. Its performance range and flexibility make it the ideal interface material for most applications.

PROPERTIES

- High thermal conductivity
- Very low total thermal transfer resistance
- Fiberglass reinforced for mechanical stability
- Very flexible
- Quick and clean handling, superior process reliability
- No thermal paste required
- UL flammability rating: UL 94 V0 (FileNo: E337894)



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We disclaim all liability for accuracy of this information. Technical detail is subject to change.

Image may differ from the original product

¹ Voltage ramp 1000 V/s

² Step-by-step voltage increments until dielectric breakdown

³ Increase of thermal resistance through adhesive by about 0,1 °C/W

PART	KU-	CG20	CG30	CG45	CG80
GENERAL PROPERTIES					
Material	Fiberglass reinforced silicone				
Filler	Thermally conductive ceramic (Boron Nitride)				
Colour	Salmon				
Gauge	mm	0,2 ^{-0,05 to +0,05}	0,3 ^{-0 to +0,1}	0,45 ^{-0,05 to +0,05}	0,8 ^{-0 to +0,1}
Density	g/cm ³	2,5	2,5	2,5	2,5
Outgassing (LMW Siloxane)	ppm	Σ D3 - D10 = <10			
MECHANICAL PROPERTIES					
Tensile strength	Mpa	25,9	24,1	20,4	9,3
Tear strength	kN/m	70	69	68	24
Hardness (Shore A)		92	92	92	92
ELECTRICAL PROPERTIES					
Breakdown Voltage (Voltage ramp) ¹	V (AC)	5000	7000	10000	19999
Breakdown Voltage (Voltage steps) ²	V (AC)	2000	3000	5000	10000
Dielectric Constant (1 kHz)		3,8	4,2	4,3	4,3
Volume Resistivity	Ωm	1,8 x 10 ¹²	1,8 x 10 ¹²	1,2 x 10 ¹²	1,0 x 10 ¹²
THERMAL PROPERTIES					
Thermal conductivity	W/mK	1,9	1,9	1,9	1,9
Thermal resistance ³ (inch ²)	°C/W	0,30	0,45	0,65	1,05
Operating temperature	°C	-60 to +200	-60 to +200	-60 to +200	-60 to +200

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